

MECHANICAL CASE OUTLINE

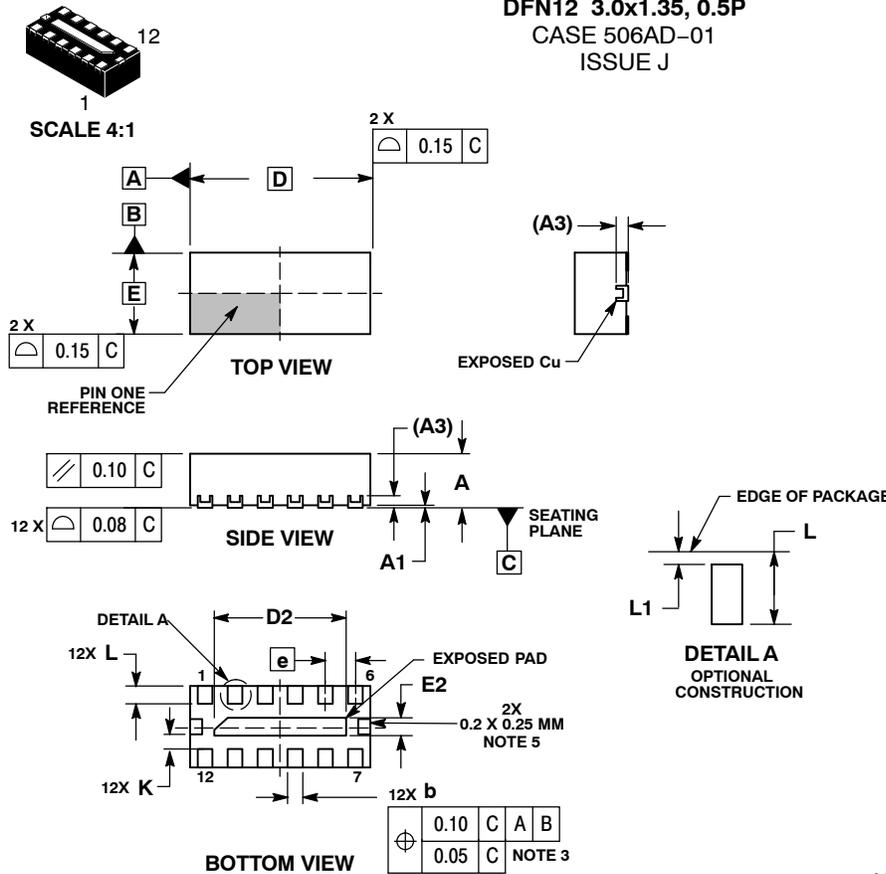
PACKAGE DIMENSIONS

ON Semiconductor®



DFN12 3.0x1.35, 0.5P
CASE 506AD-01
ISSUE J

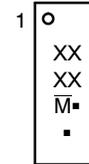
DATE 09 JUL 2008



- NOTES:
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 - CONTROLLING DIMENSION: MILLIMETER.
 - DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
 - COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
 - EXPOSED PADS CONNECTED TO DIE FLAG. USED AS TEST CONTACTS.

| DIM | MIN | MAX |
|-----|------|------|
| A | 0.80 | 1.00 |
| A1 | 0.00 | 0.05 |
| A3 | 0.20 | REF |
| b | 0.18 | 0.30 |
| D | 3.00 | BSC |
| D2 | 2.10 | 2.30 |
| E | 1.35 | BSC |
| E2 | 0.20 | 0.40 |
| e | 0.50 | BSC |
| K | 0.20 | --- |
| L | 0.20 | 0.40 |
| L1 | 0.00 | 0.15 |

GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- M = Month Code
- = Pb-Free Package

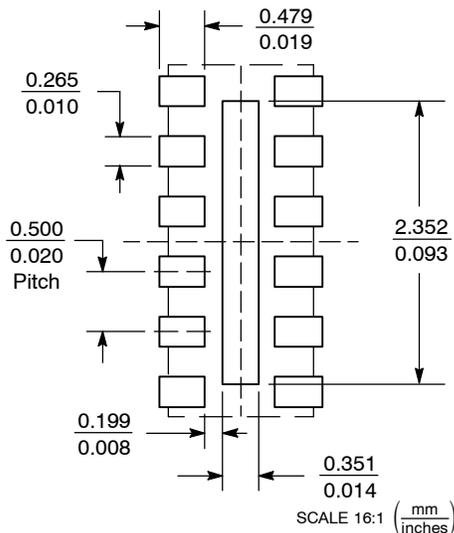
(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

STYLE 1:

- PIN 1. ANODE 1
- 2. ANODE 2
- 3. ANODE 3
- 4. ANODE 4
- 5. ANODE 5
- 6. ANODE 6
- 7. ANODE 7
- 8. ANODE 8
- 9. ANODE 9
- 10. ANODE 10
- 11. ANODE 11
- 12. ANODE 12

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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| STATUS: | ON SEMICONDUCTOR STANDARD | |
| NEW STANDARD: | | |
| DESCRIPTION: | DFN12 3.0x1.35, 0.5 MM PITCH | PAGE 1 OF 2 |

